

## 耐O2 & NF3，無添加物之超高潔淨型產品 Endurable for O2 plasma, non-filler & ultra clean performance

- 透明無添加物的特殊材料，非常適合使用在Etch, Ashing等電漿環境，針對O2, NF3氟化氣體等離子有非常優異的抵抗表現，不論是在動態件或是靜態件上的應用，例如Slit Valve, Chamber Lid, Gate Valve等都可以完美的對應

Transparent non-filler type material for Etch, Ashing and plasma application. It offers excellent resistance against O2, NF3 Fluorine plasma both in static and dynamic application such as Slit Valve, Chamber Lid, Gate Valve.



- 超高氟含量與高耐溫，適合嚴苛的製程環境  
High fluoro content & high temp. resistance, suitable for harsh environment

### ea 特性與優點 FEATURE

- 對於O2電漿環境有良好的耐受性  
Resistant to O2 plasma
- 良好的不沾粘性  
Good non-stick characteristics
- 低的元素析出性  
Low level of extractable trace elements
- 對各式化學溶劑有極優良的抗性  
Excellent resistance to solvents and chemicals

### ea 典型物理特性 PROPERTY

硬度(Shore A)	73
顏色(Color)	Dark Brown
模數(100 % Modulus, Mpa)	3
拉伸強度(Tensile strength at Break, Mpa)	13.6
延伸率(Elongation at Break, %)	230
壓縮變形率(Compression set 70 hr @ 250°C)	15.8
建議最高連續使用溫度(Temp., °C)	300

### ea 建議應用位置 APPLIED POSITION

- 反應槽密封件(Chamber Seals)
- 管線接頭密封件(Fitting Seals)
- 氣體管線密封件(Gas Inlet/Outlet Pumping Line Seals)
- 閥件密封件(Valve Seals)
- 閥門開關(Slit valve doors)

### ea 建議應用製程 APPLIED PROCESS

- 乾式蝕刻(Dry Etch)
- 濕式蝕刻(Wet Etch Acid, Base)
- 擴散(Diffusion)
- 離子植入(Ion Implant)
- 快速回火(RTP)
- 濕式去光阻(Wet Stripping Solvents)
- 濕式清潔(Wet Cleaning UPDI)